ABSTRACT

A semiconductor device includes a first contact plug penetrating a source structure, the first plug having a first portion having a first width and a second portion having a second width that is larger than the first width, a stack formed on the source structure and the first contact plug, a second contact plug penetrating the stack, the second contact plug connected to the first contact plug, a first spacer surrounding the first portion and the second portion of the first contact plug, and a second spacer surrounding the first spacer to surround the second portion of the first contact plug.

FIG. 1A